

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
150V	65mΩ@10V	5.1A

Feature

- High Speed Power Switching, logic level
- High Density Cell Design For Ultra Low On-Resistance
- Enhanced Body diode dv/dt capability
- Enhanced Avalanche Ruggedness

Application

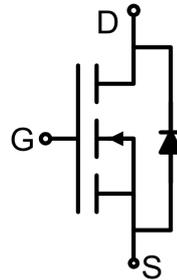
- Synchronous Rectification in SMPS
- Hard Switching and High Speed Circuit
- Power Tools
- UPS
- Motor Control

Package

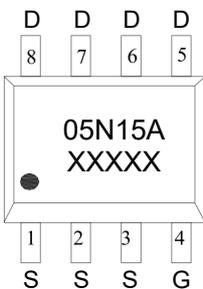


SOP-8

Circuit diagram



Marking



Absolute maximum ratings (Ta=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	150	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current	I _D	5.1	A
Pulsed Drain Current	I _{DM}	20	A
Power Dissipation	P _D	3	W
Thermal Resistance from Junction to Ambient	R _{θJA}	41.7	°C/W
Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55 ~ +150	°C

Electrical characteristics (T_A=25 °C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	150			V
Zero gate voltage drain current	I _{DSS}	V _{DS} = 150V, V _{GS} = 0V			1	μA
Gate-body leakage current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	2.5	3.3	4.5	V
Drain-source on-resistance ¹⁾	R _{DS(on)}	V _{GS} = 10V, I _D = 5.1A		55	65	mΩ
Forward transconductance ¹⁾	g _{FS}	V _{DS} = 5V, I _D = 5.1A		12.5		S
Dynamic characteristics²⁾						
Input Capacitance	C _{iss}	V _{DS} = 75V, V _{GS} = 0V, f = 1MHz		550		pF
Output Capacitance	C _{oss}			62		
Reverse Transfer Capacitance	C _{rss}			2.5		
Total Gate Charge	Q _g	V _{DS} = 75V, V _{GS} = 10V, I _D = 5.1A		8.5		nC
Gate-Source Charge	Q _{gs}			2.8		
Gate-Drain Charge	Q _{gd}			1.9		
Turn-on delay time	t _{d(on)}	V _{DD} = 75V, V _{GS} = 10V, I _D = 5.1A, R _{GEN} = 3Ω		7.5		nS
Turn-on rise time	t _r			1.4		
Turn-off delay time	t _{d(off)}			12.5		
Turn-off fall time	t _f			2.5		
Source-Drain Diode characteristics						
Diode Forward Current ¹⁾	I _S				5.1	A
Diode Forward voltage	V _{DS}	V _{GS} = 0V, I _S = 5.1A			1.2	V
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = I _S		58		nS
Reverse Recovery Charge	Q _{rr}	di/dt = 100A/μs ¹⁾		69		nC

Notes:

- 1) Pulse Test: Pulse Width < 300μs, Duty Cycle ≤2%.
- 2) Guaranteed by design, not subject to production testing.

Typical Characteristics

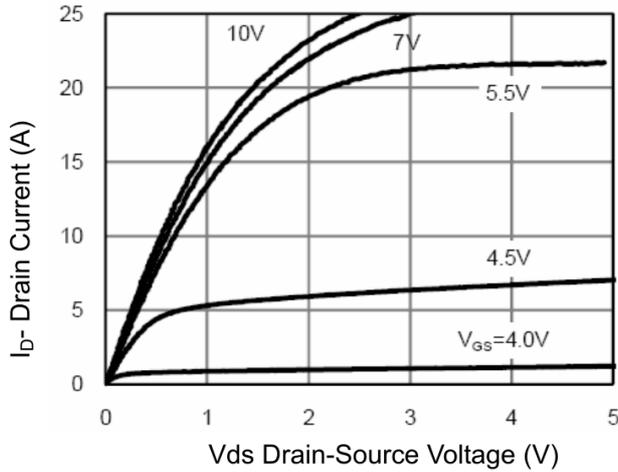


Figure 1 Output Characteristics

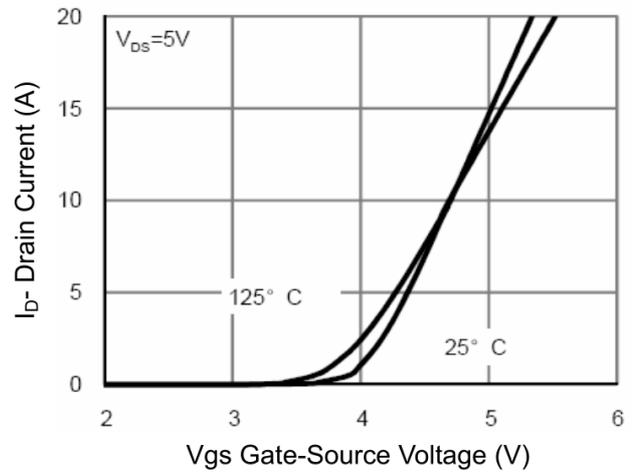


Figure 2 Transfer Characteristics

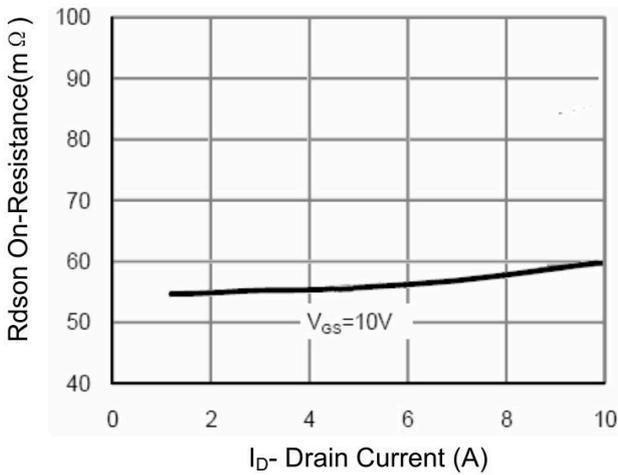


Figure 3 Rdson- Drain Current

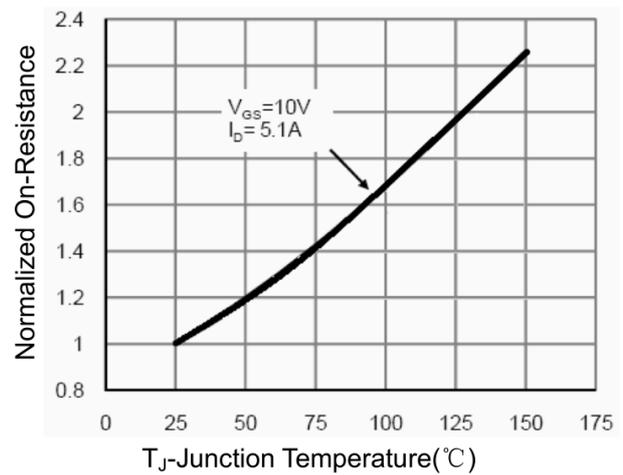


Figure 4 Rdson-Junction Temperature

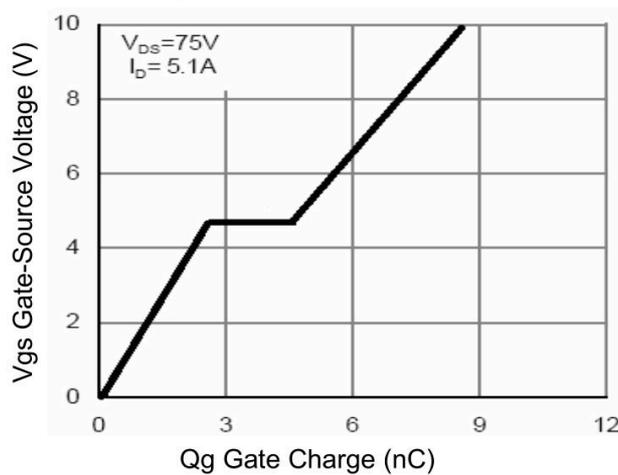


Figure 5 Gate Charge

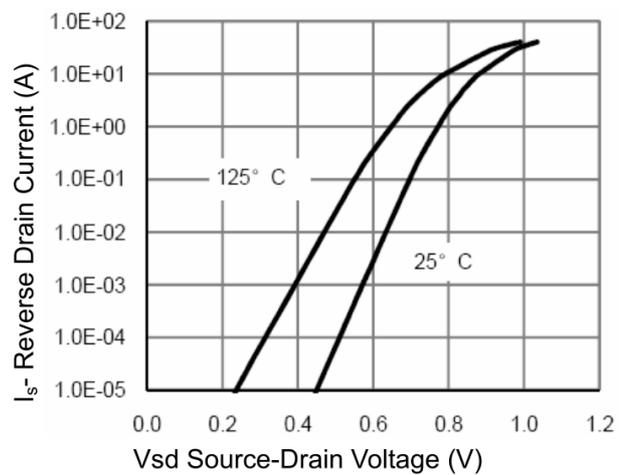


Figure 6 Source- Drain Diode Forward

Typical Characteristics

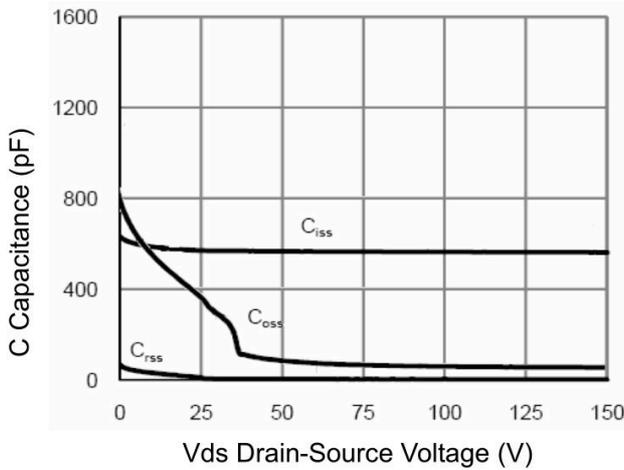


Figure 7 Capacitance vs Vds

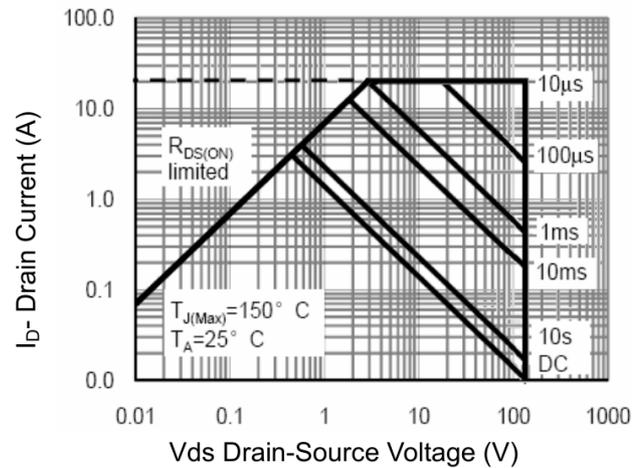


Figure 8 Safe Operation Area

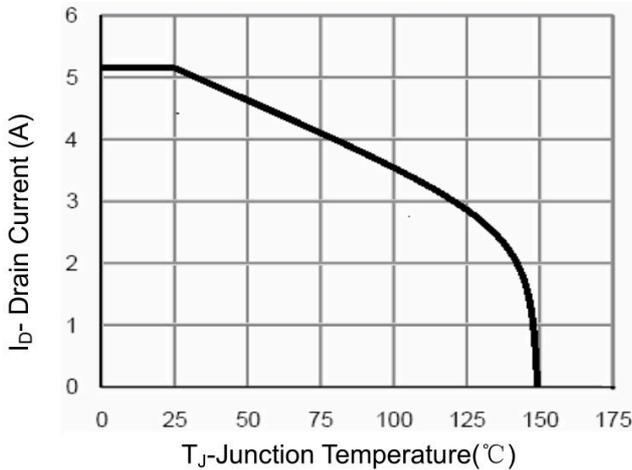


Figure 9 Current De-rating

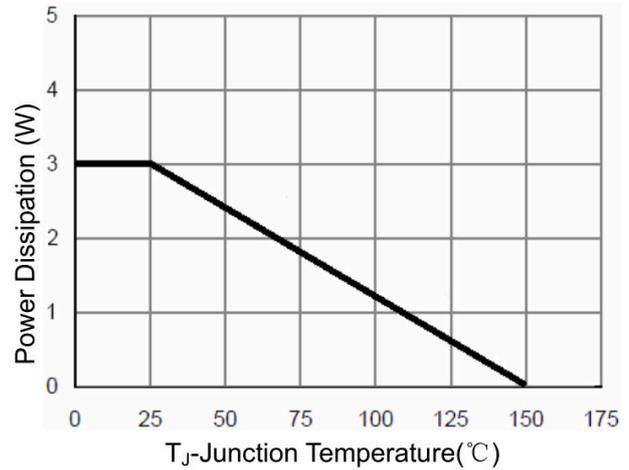


Figure 10 Power De-rating

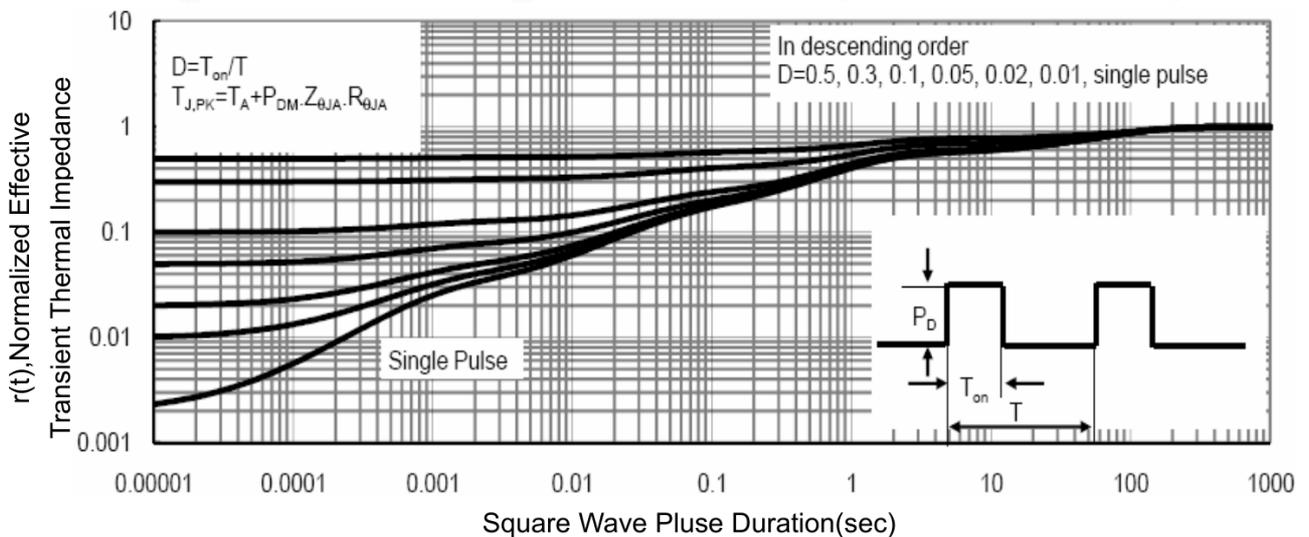
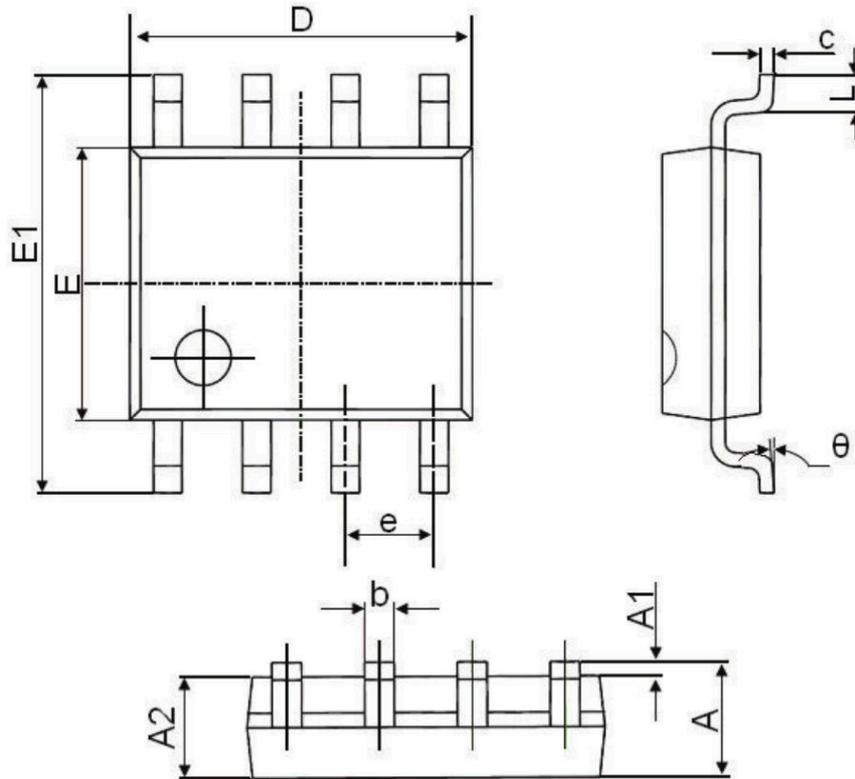


Figure 11 Normalized Maximum Transient Thermal Impedance

SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
theta	0°	8°	0°	8°